ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan	PC. Bannockl	burn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration	on of the su compasses	bstances v s all lower	vithin the manufactur level materials for w	rer listed i hich the n	tem. Note: nanufacture	if the item is an as r has engineering	sembly with low responsibility.
			Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information													
Company name* Com			ompany unique ID			Unique ID Authority				Response Date*			
nsemi							2023-06-08						
Contact Name Title - Contact					Phone - Contact*				Email - Contact*				
Product-Env-Stewards Produc			luct Enviro Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title			e - Representative			Phone - Representative*			Email - Representative*				
roduct-Env-Stewards	Product Envi	ro Compliance			NA Product-Env-Stewards@onsemi.com				m				
Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	ASX340 D0-DRE)AT2C00XPE 3R1	VGA 1/4 SOC			2023-06-08		T	A1		108.93	mg	Each
Ianufacturing Proccess Informat	tion												
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020			J-STD-020 MSL	Rating	Peak Proce	ss Body Te	emperature	e Max Time at Peak	Temperat	ure Num	ber of Reflow Cyc	les	
SnAgCu CU Alloy 3				3		260		С	30	secon	ds 3		
omments													
TTENTION: MSL 3 Rated item requires	s Bake and I	Dry Pack (after	electrical test)										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	23.9	mg		Misc.	proprietary data		0.0908	mg
			Supplier	Silicon (Si)	7440-21-3		23.5726	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2366	mg
Die Attach	2.2	mg		Bismaleimide Monomer	proprietary data		0.847	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.011	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.22	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.011	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.22	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.22	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.011	mg
			Supplier	Other Additive Agents	Proprietary Data		0.44	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.22	mg
Imaging Lens	29.31	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5426	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5426	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5426	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1545	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5426	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5426	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.4426	mg
Lid Attach	1.52	mg	Supplier	2,2-Bis(glycidyloxyphenyl)propane polymer	25085-99-8		0.38	mg
			Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		1.102	mg
			Supplier	Misc.	Proprietary Data		0.038	mg
Mold Compound	8.1	mg		Epoxy resin	proprietary data		2.0088	mg
			Supplier	Other Additive Agents	Proprietary Data		0.2592	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.81	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.779	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.243	mg
Solder Ball	24.55	mg	Supplier	Silver (Ag)	7440-22-4		0.7365	mg

			Supplier	Tin (Sn)	7440-31-5	23.6907	mg
			Supplier	Copper (Cu)	7440-50-8	0.1227	mg
Solder Mask	2.06	mg		Epoxy resin	proprietary data	0.2472	mg
			Supplier	Acrylate	Proprietary Data	0.7869	mg
			Supplier	Talc	14807-96-6	0.0556	mg
			Supplier	Miscellaneous	Trade Secret	0.0762	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	0.894	mg
Substrate Copper Foil	1.59	mg	Supplier	Copper (Cu)	7440-50-8	1.59	mg
Substrate - Core Material	7.88	mg		Epoxy resin	proprietary data	1.7076	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	6.1724	mg
Substrate Plating-Au	0.14	mg	Supplier	Gold (Au)	7440-57-5	0.14	mg
Substrate Plating-Cu	7.1	mg	Supplier	Copper (Cu)	7440-50-8	7.1	mg
Substrate Plating-Ni	0.33	mg	В	Nickel (Ni)	7440-02-0	0.33	mg
Wire Bond - Au	0.25	mg	Supplier	Gold (Au)	7440-57-5	0.25	mg